

FOR IMMEDIATE RELEASE

CONTACT SHENMAO America, Inc. Watson Tseng, General Manager E-mail: <u>watson tseng@shenmao.us</u>

SHENMAO Offers Quality Low-Temperature Solder Paste for SMT Devices

SAN JOSE, CA — May 2019 — SHENMAO America, Inc. introduces PF735-PQ10 Low Temperature Solder Paste. Qualified by a third-party organization, the PQ10 series of low temperature solder paste is made with a modified Sn/Bi alloy that has a lower melting point range from 137°~142°C to 137°~170°C. This makes it ideal for SMT devices, which can have sensitive components that cannot withstand higher temperatures.



Low-temperature solder paste has become more widely used in the assembly of surface mount technology devices because certain assemblies cannot withstand the same temperatures that are used for lead-free soldering, typically 240°-250°C. These high temperatures can damage sensitive components, causing warpage and other damage.

SHEMAO's PQ10 series of low-temperature solder paste offers some important benefits when it comes to SMT assembly. When compared with SnAgCu, the PQ10 series of low-temperature solder paste offers reduced peak reflow temperature, energy consumption, and warpage of

PCBs and components. In comparison with the Sn42/Bi58 Eutectic alloy, the PQ10 series offers better ductility, finer microstructure, and increased drop and thermal reliability.

For more information, please visit <u>www.shenmao.com</u>.

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About SHENMAO

SHENMAO is dedicated to the production of solder products including Water Soluble and Noclean Solder Paste, Laser Solder Paste, Solder Preforms, Cored Solder Wire, Wave Solder Bar Alloys, Wave Soldering Fluxes, Extremely Pure Solder Powder up to Type 8, BGA and Micro BGA Solder Sphere, Wafer Level Packaging Solder Paste and Fluxes, LED Die Attach Paste, High Performance Liquid Fluxes, Solder Preform, Solar Ribbon, Plating Anode used in PCB Fabrication, Assembly and Semiconductor Packaging Processes.